

- II. Group II, Claims 17-26 are, drawn to polishing method, classified in class 438, subclass 692.

The Examiner states that the inventions of Group I and II are distinct because the process as claimed, Group II, can be practiced with another materially different product such as one that does not require polishing a metal layer.

Applicants elect claims 1-16 and 27-32, Group I, with traverse. Claim 1 recites a composition for polishing a metal. The method claim 17 of Group II recites a method of polishing a substrate surface having metal layer with the composition of claim 1. The Examiner errs in stating the processes of Group II, such as method claim 17, can be practiced with another materially different product, such as one that does not require polishing a metal layer, since such process claims recite using a composition for polishing a metal. Withdrawal of the restriction and prosecution of claims 1-32 is respectfully requested.

Respectfully submitted,



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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

1. (Amended) A composition for [chemical mechanical] polishing a metal, the composition comprising:

- (a) a reagent comprising:
  - (i) a first moiety for oxidizing the metal; and
  - (ii) a second moiety for minimizing overetching the metal; and
- (b) a stannate salt for stabilizing the composition.

3. (Amended) The composition according to claim [3] 2, wherein the first moiety comprises a peroxide group selected from the group of a peroxycarboxylic acid group, a peroxycarboxylate group, and combinations thereof, and the resulting complexing agent comprises a carboxylic acid or a carboxylate.

17. (Amended) A method of [planarizing] polishing a substrate surface having metal layer, the method comprising:

- (a) applying a composition to a polishing pad, the composition comprising:
  - (i) a reagent comprising:
    - a first moiety for oxidizing the metal; and
    - a second moiety for minimizing overetching of [a] the metal;

and

- (ii) a stannate salt for stabilizing the composition; and
- (b) polishing the substrate surface with the composition.

23. (Amended) A method of [planarizing] polishing a substrate surface having a metal layer disposed on a barrier layer formed over a dielectric layer, the method comprising:

- (a) polishing a substrate surface using a first composition to selectively remove [a] the metal layer relative to [a] the barrier layer and [a] the dielectric film; and

(b) polishing [a] the substrate surface using a second composition to non-selectively remove the metal layer, the barrier layer, and the dielectric layer, the second composition comprising:

(i) a reagent comprising:

a first moiety for oxidizing [the] metal from the metal layer and for complexing with the metal or oxidized metal; and

a second moiety for minimizing overetching of the metal; and

(ii) a stannate salt for stabilizing the composition.

27. (Amended) A composition for [chemical mechanical] polishing a metal, the composition comprising:

(a) a reagent comprising:

(i) a first moiety comprising a peroxide group selected from the group of a peroxycarboxylic acid group, a peroxycarboxylate group, and combinations thereof; and

(ii) a second moiety comprising an alkyl group, an alkyl group derivative, an aryl group, an aryl group derivative, or combinations thereof; and

(b) a stannate salt.